

a first semiconductor chip having a pad mounting surface with a plurality of contact pads provided thereon;

a first dielectric tape member for bonding adhesively said first semiconductor chip on said chip-mounting member;

a first conductor unit for connecting electrically said contact pads of said first semiconductor chip and said first circuit traces;

a second semiconductor chip having a pad mounting surface with a plurality of contact pads provided thereon;

a second dielectric tape member for bonding adhesively said second semiconductor chip on said chip-mounting member;

a second conductor unit for connecting electrically said contact pads of said second semiconductor chip and said second circuit traces; and

a plurality of solder balls disposed on one of said first and second surfaces of said chip-mounting member, each of said solder balls being aligned with and being connected to a respective one of said plated through holes in said chip-mounting member;

wherein:

said first circuit traces and said first semiconductor chip are disposed on a same one of said first and second surfaces of said chip-mounting member;

said first dielectric tape member bonds adhesively said pad mounting surface of said first semiconductor chip on said same one of said first and second surfaces of said chip-mounting member, and is formed with a plurality of holes at positions registered with said contact pads of said first semiconductor chip;

said first conductor unit includes a plurality of conductive contact balls that are received in said holes in said first dielectric tape member to establish electrical connection between said contact pads of said first semiconductor chip and said first circuit traces;

said second dielectric tape member bonds adhesively said pad mounting surface of said second semiconductor chip on the other one of said first and second

surfaces of said chip-mounting member, and is formed with a plurality of holes at positions registered with said contact pads of said second semiconductor chip; and

said second conductor unit includes a plurality of conductive contact balls that are received in said holes in said second dielectric tape member to establish electrical connection between said contact pads of said second semiconductor chip and said second circuit traces.

21. (New) The semiconductor chip module as claimed in claim 20, wherein each of said solder balls being connected to one of said first and second circuit traces.

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